E OR M PACKAGE (TOP VIEW)

14

13 4B

12 4A

11 4Y

10 3B

9 3A

8 3Y

Vcc

1A

1B 2

1Y 3

5

6

2A 4

2Y 🛛

2B

GND

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- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
  Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

### description/ordering information

The CD74AC86 is a quadruple 2-input exclusive-OR gate. This device performs the Boolean function  $Y = A \oplus B$  or  $Y = \overline{AB} + A\overline{B}$  in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

### **ORDERING INFORMATION**

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74AC86E	CD74AC86E
–55°C to 125°C	SOIC – M	Tube	CD74AC86M	AC86M
	30IC - M	Tape and reel	CD74AC86M96	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FU	FUNCTION TABLE (each gate)											
INPUTS OUTPUT												
Α	В	Y										
L	L	L										
L	н	Н										
н	L	Н										
н	н	L										



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

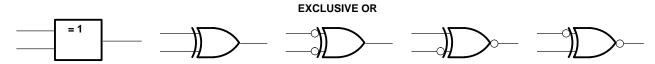


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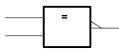
### exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



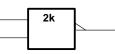
These are five equivalent exclusive-OR symbols valid for an CD74AC86 gate in positive logic; negation may be shown at any two ports.

#### LOGIC-IDENTITY ELEMENT



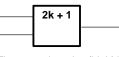
The output is active (low) if all inputs stand at the same logic level (i.e., A = B).

#### EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

#### **ODD-PARITY ELEMENT**



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	$\ldots$ -0.5 V to 6 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package	80°C/W
M package	86°C/W
Storage temperature range, T <sub>stg</sub>	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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### recommended operating conditions (see Note 3)

			T <sub>A</sub> = 2	25°C	–55°( 125		–40°C to 85°C			
			MIN	MAX	MIN	MAX	MIN	MAX		
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V	
		V <sub>CC</sub> = 1.5 V	1.2		1.2		1.2			
VIH	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		2.1		2.1		V	
		V <sub>CC</sub> = 5.5 V	3.85		3.85		3.85			
		V <sub>CC</sub> = 1.5 V		0.3		0.3		0.3		
VIL	VIL Low-level input voltage	V <sub>CC</sub> = 3 V		0.9		0.9		0.9	V	
		V <sub>CC</sub> = 5.5 V		1.65		1.65		1.65		
VI	Input voltage		0	VCC	0	VCC	0	VCC	V	
VO	Output voltage		0	VCC	0	VCC	0	VCC	V	
IОН	High-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		-24		-24		-24	mA	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		24		24		24	mA	
A+/A.v	Input transition rise or fall rate	$V_{CC}$ = 1.5 V to 3 V		50		50		50	<b>n</b> o/\/	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 3.6 V to 5.5 V		20		20		20	ns/V	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	Vcc	T <sub>A</sub> = 2	25°C	–55°( 125		–40°C to 85°C		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX	
			1.5 V	1.4		1.4		1.4		
		I <sub>OH</sub> = -50 μA	3 V	2.9		2.9		2.9		
			4.5 V	4.4		4.4		4.4		
∨он	VI = VIH or VIL	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		V
		I <sub>OH</sub> = -24 mA	4.5 V	3.94		3.7		3.8		
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85				
		I <sub>OH</sub> = -75 mA†	5.5 V					3.85		
			1.5 V		0.1		0.1		0.1	
		I <sub>OL</sub> = 50 μA	3 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1	
VOL	VI = VIH or VIL	I <sub>OL</sub> = 12 mA	3 V		0.36		0.5		0.44	V
		I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5		0.44	
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65			
		I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V						1.65	
lj	$V_I = V_{CC} \text{ or } GND$		5.5 V		±0.1		±1		±1	μA
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		4		80		40	μA
Ci					10		10		10	pF

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.



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# switching characteristics over recommended operating free-air temperature range, $V_{CC} = 1.5 \text{ V}$ , $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		–55°C to 125°C		–40°C TO 85°C	
		(001101)	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	×		135		123	
<sup>t</sup> PHL	AOIB	Ţ		135		123	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3 V $\pm$ 0.3 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55° 125		–40°C TO 85°C		UNIT
		(6611 61)	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	×	3.8	15.1	3.9	13.7	
<sup>t</sup> PHL	AOIB	T	3.8	15.1	3.9	13.7	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

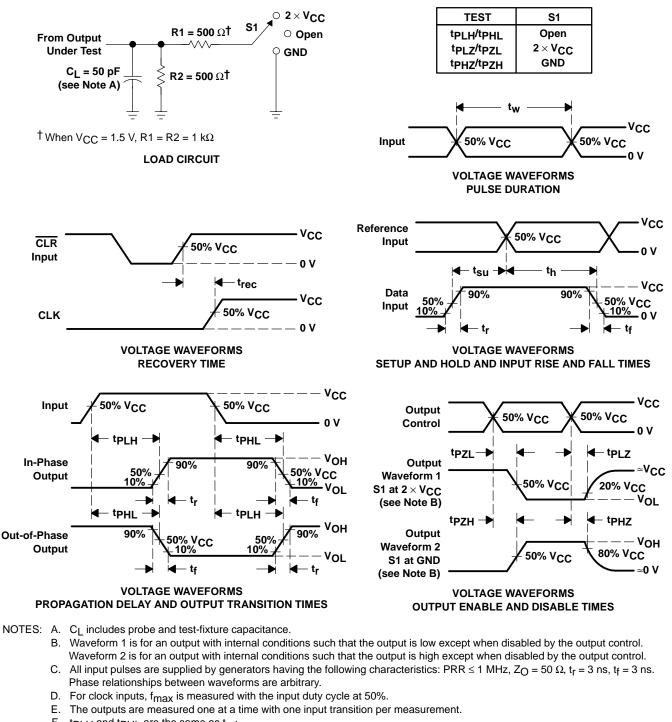
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°( 125		–40°C 85°		UNIT
		(6611 61)	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	×	2.7	10.8	2.8	9.8	
<sup>t</sup> PHL		ř	2.7	10.8	2.8	9.8	ns

## operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TYP	UNIT
Cpd	Power dissipation capacitance	57	pF



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PARAMETER MEASUREMENT INFORMATION

- F. tpLH and tpHL are the same as tpd.
- G. tp71 and tp7H are the same as ten.
- H. tPLZ and tPHZ are the same as tdis.
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD74AC86E	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC86E	Samples
CD74AC86M96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC86M	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# PACKAGE OPTION ADDENDUM

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\*A

### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



All dimensions are nominal												
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC86M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



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# PACKAGE MATERIALS INFORMATION

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC86M96	SOIC	D	14	2500	356.0	356.0	35.0

### TEXAS INSTRUMENTS

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## TUBE



## - B - Alignment groove width

\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CD74AC86E	N	PDIP	14	25	506	13.97	11230	4.32
CD74AC86E	N	PDIP	14	25	506	13.97	11230	4.32

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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